

# Opto-Isolator Selection Guidelines: TPS2384 I<sup>2</sup>C Interface

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## ABSTRACT

The TPS2384 is a quad-port power sourcing equipment power manager (PSEPM) which is compliant to the Power-over-Ethernet (PoE) IEEE 802.3af standard. When ground isolation is required between the micro-controller and Ethernet ports, opto-isolators can be placed between the TPS2384 I<sup>2</sup>C interface and micro-controller. This document provides design guideline specifics for selection of the opto-isolator devices.

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## 1 Introduction

In some applications, electrical ground isolation between the 48V referenced TPS2384 circuitry and master controller (MC) may be required. While other isolator configurations are possible, an optical-isolator implementation is discussed in this report.

Two significant isolator design issues are considered:

- Impact on TPS2384 digital I<sup>2</sup>C timing when inserting opto-isolators in the control path.
- Opto-isolator power consumption from the TPS2384 digital supply (V3.3 — pin 24).

Figure 1 illustrates a typical opto-isolator connection between the MC and the TPS2384.

First Pass Timing

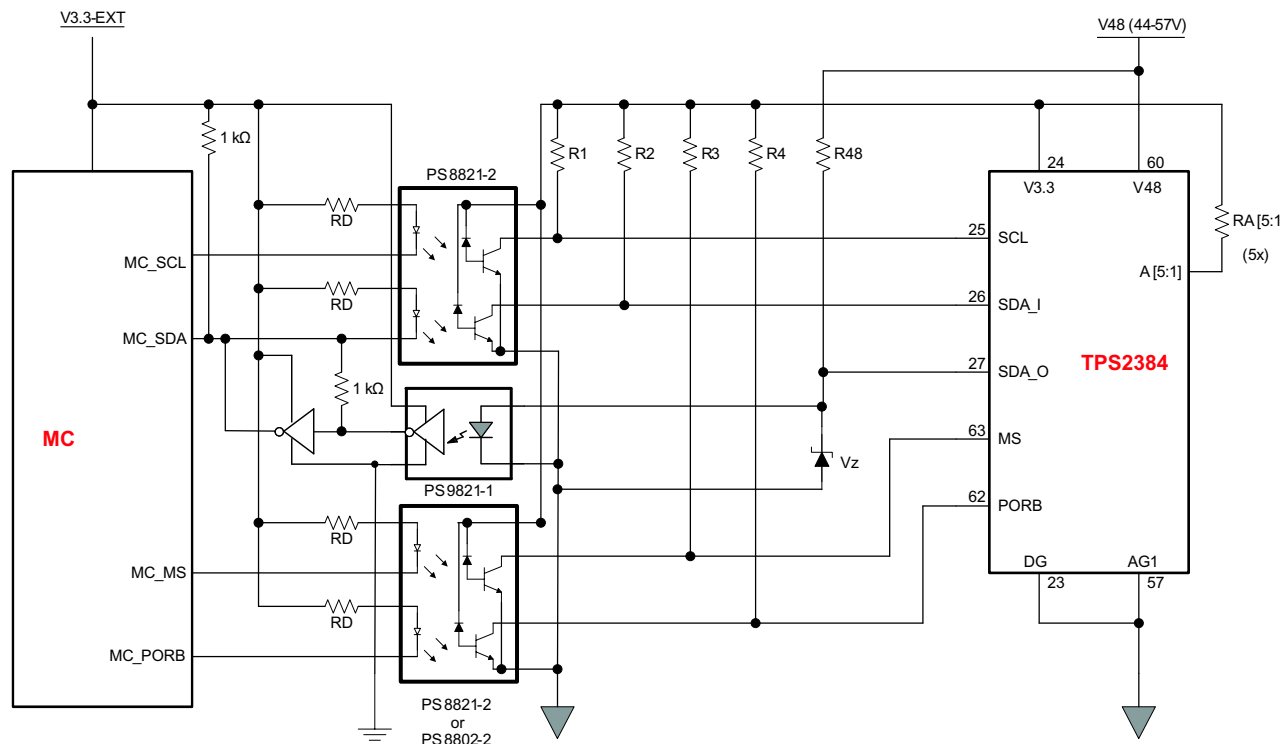


Figure 1. Basic Interface Diagram

## 2 First Pass Timing

The TPS2384 data sheet digital I<sup>2</sup>C timing requirements are summarized in Table 1. These timing requirements mirror the requirements for fast mode (F/S) devices outlined in the Phillips I<sup>2</sup>C specification. The opto-isolator propagation delay characteristics can constrain and possibly necessitate alteration of the MC output timing requirements.

Table 1. Digital I<sup>2</sup>C Timing Requirements

PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNITS
SCL clock frequency		0		400	kHz
Pulse duration	SCL high	0.6			μs
	SCL low	1.3			
Rise time, SCL to SDA				0.3	μs
Fall time, SCL to SDA				0.3	μs
Setup time, SDA to SCL		0.25			μs
Hold time, SCL to SDA		0.3		0.9	μs
Bus free time between start and stop		1.3			μs
Setup time, SCL to start condition		0.6			μs
Hold time, start condition to SCL		0.6			μs
Setup time, SCL to stop condition		0.6			μs
Delay time, SCL to SCL <sub>INT</sub> , t <sub>d</sub> (SCL)			0.5 <sup>(1)</sup>	0.9 <sup>(1)</sup>	μs

(1) t<sub>d</sub>(SCL) is the TPS2384 internal clock delay.

Selection of the opto-isolator type should also consider end to end signal polarity and MC output drive type. The circuit in [Figure 1](#) implements *inverting* opto-isolators for the SCL and SDA\_I inputs but since the MC drives the LED cathode; no net polarity inversion takes place.

Also of note in [Figure 1](#) is the SDA\_O signal drive implementation. To minimize V3.3 loading, the SDA\_O signal derives its LED anode drive current from V48. Since this drive implementation induces a polarity change, an inverter is required between the opto-isolator output and the MC. This inverter must be an open drain type to be compatible with the I<sup>2</sup>C specification and have minimal impact on timing. The zener diode Vz (5.6V), adds a layer of voltage protection to the opto-isolator LED and SDA\_O. R48 should be chosen with power dissipation (1/2W) and LED bias current in mind.

## 2.1 SCL/SDA\_I Setup and Hold Considerations

The I<sup>2</sup>C standard states that SDA\_I must be stable during the SCL logic high time (including SDA\_I setup and hold times), or in other words SDA\_I can only change state when SCL is a valid low.  $t_{trans}$  is the allowable SDA\_I state transition time window (during SCL low) and bounds the rising and falling edge propagation delay requirements of the opto-isolators. [Table 2](#) shows  $t_{trans}$  for minimum and maximum hold times,  $t_h$ .

$$t_{trans} = t_{low} - t_{su(min)} - t_h$$

**Table 2. Acceptable SDA Transition Time Window**

$t_{trans}$ (μs)	$t_{low}$ (μs)	$t_{su}$ (μs)	$t_h$ (μs)
0.75	1.3	0.25	0.3
0.15	1.3	0.25	0.9

In general, if the rising and falling edge propagation delays of the SCL and SDA\_I opto-isolators track each other, are sufficiently small, and the MC meets the requirements of the I<sup>2</sup>C standard, then input signal timing can be met. Similarly, start, restart, and stop conditions have setup and hold requirements of  $t_{stop/start} = 0.6 \mu s$  which should also be considered.

## 2.2 SDA\_O Timing Considerations

The TPS2384 internal SCL delay,  $t_{d(SCL)}$  should be considered for device reads. SDA\_O transition timing occurs on the falling edge of the TPS2384 internal SCL signal as illustrated in [Figure 2](#). The SDA\_O opto-isolator is restricted to faster devices so that data arrives at the MC within the required setup and hold times.  $t_{d(SCL)}$ ,  $t_{PLH(SCL)}$ ,  $t_{PHL(SCL)}$ , and  $t_{su(MC)}$  delays bound opto-isolator propagation delays on the SDA\_O signal. Also note that the SDA\_O opto-isolator (and inverter) are powered by V3.3-EXT and do not impact V3.3 loading.

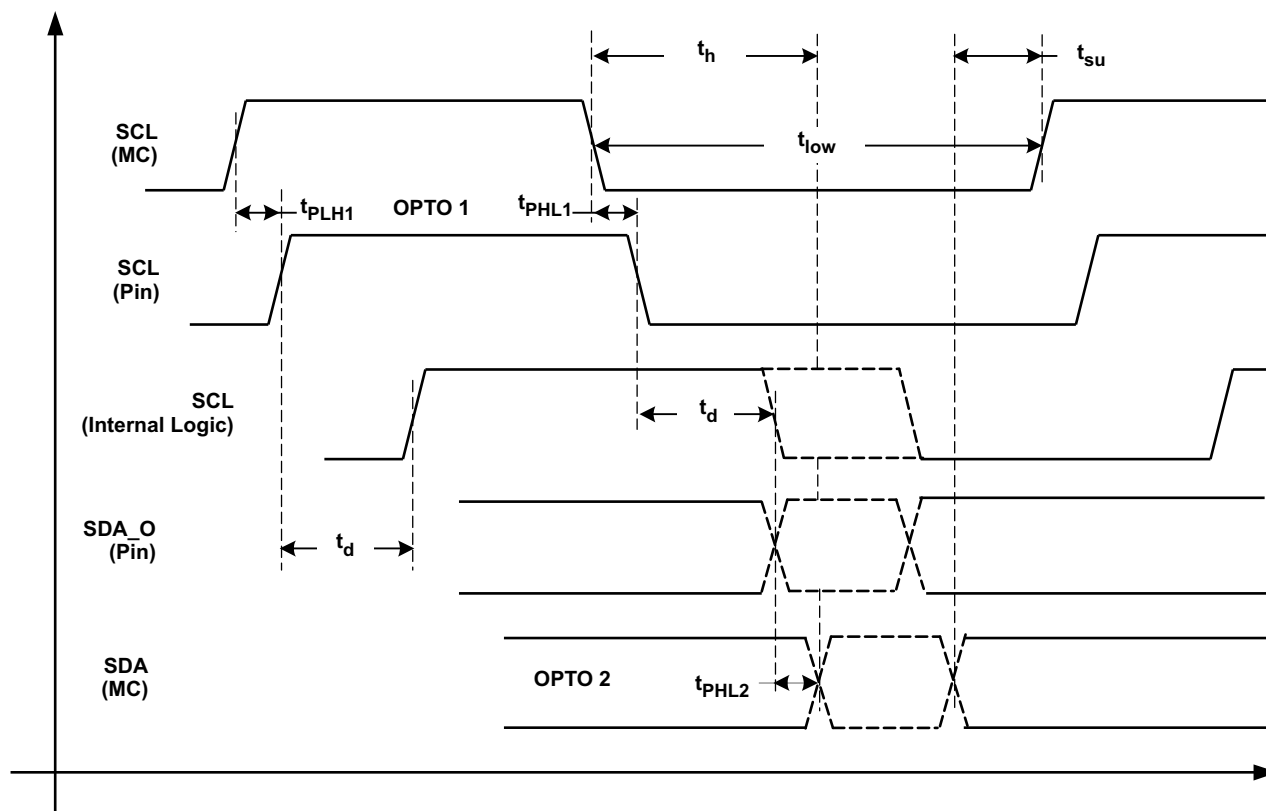

**Figure 2. TPS2384 Internal SCL Delay**

Table 3 shows target  $t_{PHL}$  (total sum for SCL and SDA\_O opto-isolators) values that can be derived from the following equations.

$$t_{h(\min)} < t_{PHL} + t_{d(SCL)} < t_{h(\max)}$$

$$t_{h(\min)} - t_{d(SCL)} < t_{PHL} < t_{h(\max)} - t_{d(SCL)}$$

and

$$t_{PHL} + t_{d(SCL)} < t_{low} - t_{su}$$

$$t_{PHL} < t_{low} - t_{su} - t_{d(SCL)}$$

**Table 3. Opto-Isolator  $t_{PHL}$  Values**

CONSIDERING SDA_O HOLD REQUIREMENTS			CONSIDERING SDA_O SETUP REQUIREMENTS		
$t_{PHL}$ ( $\mu$ s)	$t_h$ ( $\mu$ s)	$t_{d(SCL)}$ ( $\mu$ s)	$t_{PHL}$ ( $\mu$ s)	$t_{su}$ ( $\mu$ s)	$t_{d(SCL)}$ ( $\mu$ s)
> -0.2	0.3	0.5	< 0.55	0.25	0.50
> -0.6	0.3	0.9	< 0.15	0.25	0.90
< 0.4	0.9	0.5			
< 0.0	0.9	0.9			

### 3 Opto-Isolator Selection

For the SCL and SDA\_I signals, a medium-fast, low power, dual opto-isolator configuration is desired. For the SDA\_O signal, a fast, medium power, single opto-isolator is desired, and for the low speed MS and PORB signals, a slow, low power, dual opto-isolator configuration is desired. Three NEC Electronics photo couplers were selected and the relevant details are summarized in Table 4.



#### 4.1 DC Considerations

R3/R4: Select a value for these resistors based on MS/PORB threshold of 1.5V (and 150mV hysteresis) and the MS/PORB internal 50-kΩ resistor pull-down ( $R_{INT}$ ).

$$V_{3.3(max)} \times \frac{R_{INT}/N}{R_{INT}/N + R3} > V_{TH(max)} = V_{TH(nom)} + V_{HYST}$$

Let :  $R_{INT} = 0.8 \times R_{INT(nom)} = 40 \text{ k}\Omega$ ,  $N = \text{Number of TPS2384 Devices}$

$$R3 < \frac{R_{INT}}{N} \times \left[ \frac{V_{3.3(min)}}{V_{TH(max)}} - 1 \right] \text{ For } N = 2, R3 < \left( \frac{40k}{2} \right) \times \left( \frac{3}{1.65} - 1 \right) = 16.4 \text{ k}\Omega$$

R1/R2: Select R1/R2 for simultaneous SCL/SDA\_I low (for V3.3 output current) and minimize R1/R2 for rise time signal considerations.

$$I_{3.3(max)}(R1 \& R2) = 3 \text{ mA} - I_{opto} - I_{addr} - I_{R3/R4}$$

$$I_{3.3(max)}(R1 \& R2) = 3 \text{ mA} - 400 \mu\text{A} - 50 \mu\text{A} - 404 \mu\text{A} = 2.1 \text{ mA}$$

$$R1/R2 > \frac{V_{3.3}}{0.5 \times I_{3.3(max)}(R1 \& R2)} = \frac{3.3}{0.5 \times 2.1 \text{ mA}} = 3.1 \text{ k}\Omega$$

For  $V_{3.3(max)} = 3.7 \text{ V}$ ,  $R1/R2 > 3.5 \text{ k}\Omega$

Table 5 summarizes the DC load requirement targets.

**Table 5. DC Load Current Summary**

	<b>V3.3 = 3.3V</b>	
<b>Load</b>	<b>Target <math>I_{LD}</math></b>	<b>Target <math>R_{PU}</math></b>
Address	50 $\mu\text{A}$	
PS8821-2	200 $\mu\text{A}$	
PS8802-2	200 $\mu\text{A}$	
R1	1.05 mA	3.1 k $\Omega$
R2	1.05 mA	3.1 k $\Omega$
R3	202 $\mu\text{A}$	16.4 k $\Omega$
R4	202 $\mu\text{A}$	16.4 k $\Omega$
	$I_{SUM} = 3.0 \text{ mA}$	

#### 4.2 AC Considerations

Bulk energy storage capacitance: Determine beneficial effects of V3.3 capacitance which sources current peaks during simultaneous *logic low* conditions. Considering V3.3 ( $V_S$ ) with series source impedance  $R_S$ , minimum  $R_L$  ( $R1 \parallel R2$ ) can be determined so that V3.3 does not fall below 1.65V ( $V_{TH} + V_{HYST}$ ) during simultaneous logic low (with  $I_S = 2.1 \text{ mA}$ ). [Figure 4](#) shows the circuit model.

$$R_L = R_S = 1.65 \text{ V} / 0.0021 = 786 \Omega$$

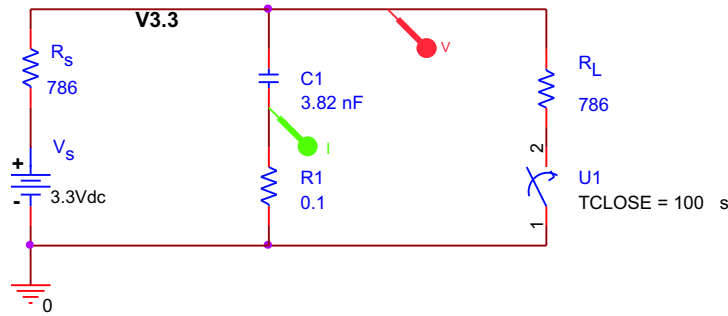


Figure 4. AC Load Model for V3.3

Target C1 value required to keep V3.3 above 1.65 V during U1 on time:

For I<sup>2</sup>C bus speed = 100 kHz,  $t_{low(max)} = 6 \mu s$  (very fast rise/fall times)

Target  $4 \times \tau$  (98% droop) =  $t_{low(max)}$

$$t_{low(max)} = 4 \times R \times C1 : R = R_L \parallel R_S = \frac{R_L}{2}$$

$$t_{low(max)} = 2 \times R_L \times C1$$

$$C1(min) = \frac{t_{low(max)}}{2 \times R_L} = \frac{6 \mu s}{2 \times 786} = 3.82 \text{ nF}$$

$$R_L = R1 \parallel R2; R1(min) = R2(min) = 2 \times R_L = 2 \times 786 = 1572 \Omega$$

This shows that a significantly small C1 is adequate to support V3.3 during relatively slow I<sup>2</sup>C bus access. A reasonable bypass capacitor value of 0.1 $\mu$ F located at the V3.3 pin of the TPS2384 and at each pin of the dual opto-isolators provides good AC voltage stability. Assuming C1 = 0.3 $\mu$ F and R1 = R2 = 1572  $\Omega$ , yields  $t_{low(max)} = 472 \mu s$ . This equates to a minimum I<sup>2</sup>C bus access speed of 1.27 kHz. So, targeting R1 and R2 values between the minimum AC value (1572  $\Omega$ ) and the minimum DC value (3.1 k $\Omega$ ) provides good AC and DC performance.

The designer must keep in mind that the timing parameters detailed in Table 4 and used in Section 5 are based on I<sub>F</sub> (set by RD in Figure 1 and Figure 3) and R<sub>L</sub> (R1, R2, R3, R4 in Figure 1 and Figure 3) values specified in the opto-isolator manufacturers data sheet. Deviation from these values will have an impact on timing and must be evaluated.

## 5 Final Timing Analysis

MC writes must meet the TPS2384 setup and hold times by synchronizing data transitions to occur within the acceptable data transition window outlined in Section 2.1. MC reads from the TPS2384 must meet the MC setup and hold times as outlined in Section 2.2. The following equations define the acceptable data transition window times (during SCL low) for reads and writes.

Read Access (400 kHz SCL,  $t_0$  at SCL rising edge):

$$t_{accept1} = t_{high} + t_{h(max)}$$

$$t_{accept2} = t_{period} - t_{su(MC-min)}$$

Write Access (400 kHz SCL,  $t_0$  at SCL rising edge):

$$t_{accept1} = t_{high} + t_{h(max)}$$

$$t_{accept2} = t_{period} - t_{su(2384-min)}$$

NOTE: Rise and fall times are ignored here but must be considered by the designer.

Table 6 illustrates the impact of timing parameter variations during reads and writes.  $t_{MC}$  represents the delay variability that must be accounted for when designing SCL/SDA timing. Designers should target the data transitions to occur within the acceptable time windows,  $t_{accept1}$  and  $t_{accept2}$  for each condition.

**Table 6. Timing Budget Summary**

<b>Reads</b>								
Min	0.1	0.6	0.1	0.5		$t_h = 0.9$		
Max	0.9	1.2	0.6	0.9				
$t_o$	$t_{PLH}$	$t_{high}$	$t_{PHL}$	$t_d$	$t_{p-opto2}$	$t_{mc}$	$t_{accept1}$	$t_{accept2}$
0	0.1	0.6	0.1	0.5	0.1	1.4	1.5	2.4
0	0.1	0.6	0.1	0.9	0.1	1.8	1.5	2.4
0	0.1	0.6	0.6	0.5	0.1	1.9	1.5	2.4
0	0.1	0.6	0.6	0.9	0.1	2.3	1.5	2.4
0	0.1	1.2	0.1	0.5	0.1	2	2.1	2.4
0	0.1	1.2	0.1	0.9	0.1	2.4	2.1	2.4
0	0.1	1.2	0.6	0.5	0.1	2.5	2.1	2.4
0	0.1	1.2	0.6	0.9	0.1	2.9	2.1	2.4
0	0.9	0.6	0.1	0.5	0.1	2.2	1.5	2.4
0	0.9	0.6	0.1	0.9	0.1	2.6	1.5	2.4
0	0.9	0.6	0.6	0.5	0.1	2.7	1.5	2.4
0	0.9	0.6	0.6	0.9	0.1	3.1	1.5	2.4
0	0.9	1.2	0.1	0.5	0.1	2.8	2.1	2.4
0	0.9	1.2	0.1	0.9	0.1	3.2	2.1	2.4
0	0.9	1.2	0.6	0.5	0.1	3.3	2.1	2.4
0	0.9	1.2	0.6	0.9	0.1	3.7	2.1	2.4
<b>Writes</b>								
Min	0.1	0.6	0.1		$t_h = 0.9$			
Max	0.9	1.2	0.6					
$t_o$	$t_{PLH}$	$t_{high}$	$t_{PHL}$	$t_{mc}$	$t_{accept1}$	$t_{accept2}$		
0	0.1	0.6	0.1	0.8	1.5	2.25		
0	0.1	0.6	0.6	1.3	1.5	2.25		
0	0.1	1.2	0.1	1.4	2.1	2.25		
0	0.1	1.2	0.6	1.9	2.1	2.25		
0	0.9	0.6	0.1	1.6	1.5	2.25		
0	0.9	0.6	0.6	2.1	1.5	2.25		
0	0.9	1.2	0.1	2.2	2.1	2.25		
0	0.9	1.2	0.6	2.7	2.1	2.25		

## 6 Conclusion

This application of opto-isolator interface to the TPS2384 has been implemented for use with the MSP430 micro-controller. In all cases, the MC operating characteristics should be studied carefully and in some cases tailored to meet I<sup>2</sup>C bus timing requirements. This may require SCL duty cycle adjustment and/or SDA transition time adjustment with respect to SCL. In some cases, this can be accomplished by slowing the I<sup>2</sup>C bus speed to less than 400 kHz; however, this bus speed slowdown may limit the total number of controllable ports in larger systems.

## 7 References

1. *TPS2384, Quad Integrated Power Sourcing Equipment Power Manager* ([SLUS634](#))
2. *TPS2384, Users Guide* ([SLVU126B](#))
3. *I<sup>2</sup>C Bus Specification*



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